from the electronic component. The arrangement of these contact areas is closely linked to the position of the contacts of the electronic component and to other conditions, such as necessary distance between the contacts, spatial conditions, etc. Here, the fixed arrangement of the contacts of the test head cannot normally be implemented or can be implemented only to a slight extent.

One or more hardware interfaces is/are therefore normally used and connect the contacts of the test base, said contacts facing away from the electronic component, to the contacts of the test head. Such hardware interfaces, which on one side contain contact areas adapted to the test base and on the opposite side contain contact pins adapted to the test head, are known. In order to stabilise these contact pins, they have to be cast into the hardware interface.

Since the contact pins have to be positioned very accurately, it is relatively complex and costly to cast in the contact pins. Nevertheless, the risk that these contact pins will be damaged when modified to another electronic component or during storage is very high. If only a single contact pin is damaged or broken off, the entire hardware interface is useless and has to be replaced, since it is not possible, with cast-in contact pins, to change these individually.

The object of the invention is to design a device for testing electronic components according to the preamble of Claim 1, such that signals can be exchanged between the test base and the test head with high transmission reliability, and the used hardware interfaces are easily structured, can be produced cost-effectively and are robust.

The object is solved in accordance with the invention by a device for testing electronic components having the features of Claim 1. In accordance with the invention, a device for testing electronic components including at least one test base for contacting the electronic components and including a test head, which is coupled electrically to the test base, is disclosed. ~~i~~In order to forward signals between the test base and test head, an adapter board is provided, which, on its side facing the test base, has contact areas which

are adapted to the position of contacts of the test base, and, on its side facing away from the test base, is provided with contact sockets which are adapted to the position of contact pins of the test